Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP ENVY
HP ENVY Notebook
HP ENVY m7 Notebook
HP ENVY Notebook 17 /HP ENVY 17
HP ENVY m7

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery, RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>PWR cord , Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

<table>
<thead>
<tr>
<th>Components and waste containing asbestos</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>Philip #1 / TORX T</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery pack
2. Remove ODD
3. Remove log low
4. Remove Thermal module
5. Remove Speaker
6. Remove HDD & NGFF & WLAN
7. Remove DDR & Finger Print Module & USB Board
8. Remove M/B
9. Remove LCD Ass’y
10. Remove DC-in Cable
11. Remove Click PAD
12. Remove K/B
13. Remove LCD Cover Ass’y (Touch SKU)
14. Remove WLAN Ant. (Touch SKU)
15. Remove Hinge (Touch SKU)
16. Remove eDP Cable (Touch SKU)
17. Remove Camera Module & Control Board (Touch SKU)
18. Remove Panel BRK & Panel (Touch SKU)
19. Remove Bezel (Non Touch SKU)
20. Remove WLAN Ant. (Non Touch SKU)
21. Remove Panel BRK & Panel (Non Touch SKU)
22. Remove Hinge (Non Touch SKU)
23. Remove eDP Cable & Camera module (Non Touch SKU)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove battery pack

Step 2 Remove ODD

Step 3 Remove log low

Step 4 Remove Thermal module

Step 5 Remove Speaker

Step 6 Remove HDD & NGFF & WLAN

PSG instructions for this template are available at EL-MF877-01
Step 7 Remove DDR & Finger Print Module & USB Board

Step 8 Remove M/B

Step 9 Remove LCD ass’y

Step 10 Remove DC-in Cable

Step 11 Remove Click PAD

Step 12 Remove K/B

PSG instructions for this template are available at EL-MF877-01
Step 13 Remove LCD Cover Ass’y
(Touch SKU)

Step 14 Remove WLAN Ant.
(Touch SKU)

Step 15 Remove Hinge
(Touch SKU)

Step 16 Remove eDP Cable
(Touch SKU)
Step 17  Remove Camera Module & Control Board
(Touch SKU)

Step 18 Remove Panel BRK & Panel
(Touch SKU)

Step 19  Remove Bezel
(Non Touch SKU)

Step 20  Remove WLAN Ant.
(Non Touch SKU)
Step 21  Remove Panel BRK & Panel
          (Non Touch SKU)

Step 22  Remove Hinge
          (Non Touch SKU)

Step 23 Remove eDP Cable & Camera module
          (Non Touch SKU)